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December 2014

FCP110N65F

N-Channel SuperFET[®] II FRFET[®] MOSFET 650 V, 35 A, 110 m Ω

Features

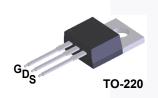
- 700 V @ T_J = 150°C
- Typ. $R_{DS(on)} = 96 \text{ m}\Omega \text{ (Typ.)}$
- Ultra Low Gate Charge (Typ. Q_q = 98 nC)
- Low Effective Output Capacitance (Typ. C_{oss(eff.)} = 464 pF)
- · 100% Avalanche Tested
- · RoHS Compliant

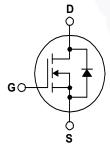
Applications

- LCD / LED / PDP TV Telecom / Server Power Supplies
- · Solar Inverter
- AC DC Power Supply

Description

SuperFET® II MOSFET is Fairchild Semiconductor's brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This technology is tailored to minimize conduction loss, provide superior switching performance, dv/dt rate and higher avalanche energy. Consequently, SuperFET II MOSFET is very suitable for the switching power applications such as PFC, server/telecom power, FPD TV power, ATX power and industrial power applications. SuperFET II FRFET® MOSFET's optimized body diode reverse recovery performance can remove additional component and improve system reliability.





Absolute Maximum Ratings T_C = 25°C unless otherwise noted.

Symbol		Parameter		FCP110N65F	Unit
V _{DSS}	Drain to Source Voltage			650	V
	Cata ta Carras Valtaria	- DC		±20	V
V_{GSS}	Gate to Source Voltage	- AC	(f > 1 Hz)	±30	V
. \	Drain Current	- Continuous (T _C = 25°C)		35	^
ID	Drain Current	- Continuous (T _C = 100°C)		24	A
I _{DM}	Drain Current	- Pulsed	(Note 1)	105	Α
E _{AS}	Single Pulsed Avalanche Ene	rgy	(Note 2)	809	mJ
I _{AR}	Avalanche Current		(Note 1)	8	Α
E _{AR}	Repetitive Avalanche Energy		(Note 1)	3.57	mJ
dv/dt	MOSFET dv/dt		100	V/ns	
dv/dt	Peak Diode Recovery dv/dt		(Note 3)	50	V/IIS
D	Dower Discipation	(T _C = 25°C)		357	W
P_{D}	Power Dissipation	- Derate Above 25°C		2.86	W/oC
T _J , T _{STG}	Operating and Storage Tempe	erature Range		-55 to +150	οС
T _L	Maximum Lead Temperature 1/8" from Case for 5 Seconds	•		300	°C

Thermal Characteristics

Symbol	Parameter	FCP110N65F	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	0.35	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	62.5	C/VV

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FCP110N65F	FCP110N65F	TO-220	Tube	N/A	N/A	50 units

Test Conditions

Min.

Тур.

Max.

Unit

Electrical Characteristics $T_C = 25^{\circ}C$ unless otherwise noted. Parameter

Off Chara	acteristics					
BV _{DSS}	Drain to Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 10 \text{ mA}, T_J = 25^{\circ}\text{C}$	650	-	-	V
		$V_{GS} = 0 \text{ V}, I_D = 10 \text{ mA}, T_J = 150^{\circ}\text{C}$	700	-	-	
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 10 mA, Referenced to 25°C	-	0.72	-	V/°C
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 650 \text{ V}, V_{GS} = 0 \text{ V}$	-	-	10	^
		$V_{DS} = 520 \text{ V}, T_{C} = 125^{\circ}\text{C}$	-	110	-	μА
I _{GSS}	Gate to Body Leakage Current	V _{GS} = ±20 V, V _{DS} = 0 V	-	-	±100	nA

On Characteristics

Symbol

$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 3.5 \text{ mA}$	3	-	5	V
R _{DS(on)}	Static Drain to Source On Resistance	$V_{GS} = 10 \text{ V}, I_D = 17.5 \text{ A}$	-	96	110	mΩ
9 _{FS}	Forward Transconductance	V _{DS} = 20 V, I _D = 17.5 A	-	30	1	S

Dynamic Characteristics

C _{iss}	Input Capacitance	V = 400 V V = 0 V	\ -	3680	4895	pF
C _{oss}	Output Capacitance	$V_{DS} = 100 \text{ V}, V_{GS} = 0 \text{ V},$ $V_{DS} = 100 \text{ W}$	-	110	145	pF
C _{rss}	Reverse Transfer Capacitance	- 1 WI 12	-	0.65	-	pF
Coss	Output Capacitance	V _{DS} = 380 V, V _{GS} = 0 V, f = 1 MHz	-\	65	-	pF
C _{oss(eff.)}	Effective Output Capacitance	V _{DS} = 0 V to 400 V, V _{GS} = 0 V	-	464	-	pF
Q _{g(tot)}	Total Gate Charge at 10V	V _{DS} = 380 V, I _D = 17.5 A,	-	98	145	nC
Q _{gs}	Gate to Source Gate Charge	V _{GS} = 10 V	-	20	-	nC
Q_{gd}	Gate to Drain "Miller" Charge	(Note 4)	-	43	-	nC
ESR	Equivalent Series Resistance	f = 1 MHz	-	0.7	-	Ω

Switching Characteristics

t _{d(on)}	Turn-On Delay Time			-	31	72	ns
t _r	Turn-On Rise Time	V _{DD} = 380 V, I _D = 17.5 A,		-/	21	52	ns
t _{d(off)}	Turn-Off Delay Time	$V_{GS} = 10 \text{ V}, R_g = 4.7 \Omega$		-	89	188	ns
t _f	Turn-Off Fall Time	1)	Note 4)	_//-	5.7	21	ns

Drain-Source Diode Characteristics

I _S	Maximum Continuous Drain to Source Diod	Maximum Continuous Drain to Source Diode Forward Current			35	Α
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current			-	105	Α
V_{SD}	Drain to Source Diode Forward Voltage	Drain to Source Diode Forward Voltage V _{GS} = 0 V, I _{SD} = 17.5 A		-	1.2	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _{SD} = 17.5 A,	-	133	-	ns
Q _{rr}	Reverse Recovery Charge	$dI_F/dt = 100 A/\mu s$	-	0.67	-	μС

- 1. Repetitive rating: pulse width limited by maximum junction temperature.
- 2. I_{AS} = 8 A, R_G = 25 Ω , starting T_J = 25°C.
- 3. I $_{SD} \leq$ 17.5 A, di/dt \leq 200 A/µs, V $_{DD} \leq$ 380 V, starting T $_{J}$ = 25°C.
- 4. Essentially independent of operating temperature typical characteristics.

Typical Performance Characteristics

Figure 1. On-Region Characteristics

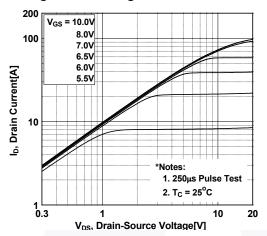


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

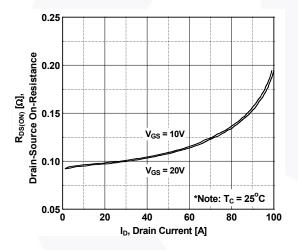


Figure 5. Capacitance Characteristics

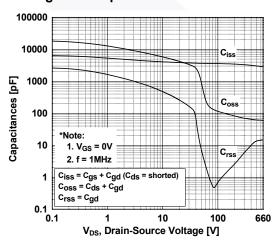


Figure 2. Transfer Characteristics

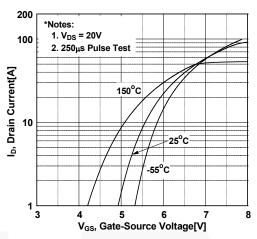


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

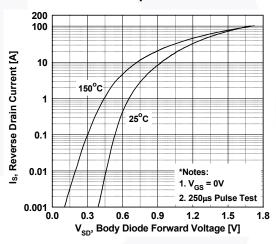
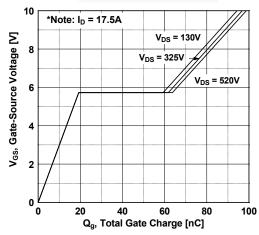


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

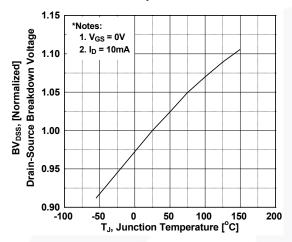


Figure 9. Maximum Safe Operating Area

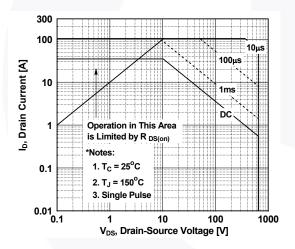


Figure 11. Eoss vs. Drain to Source Voltage

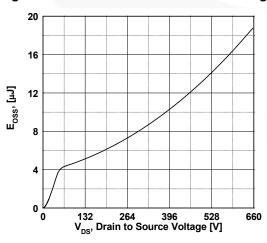


Figure 8. On-Resistance Variation vs. Temperature

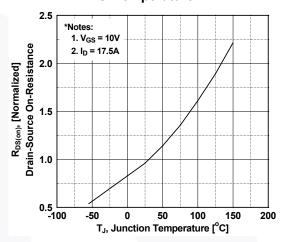
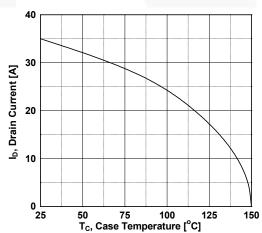
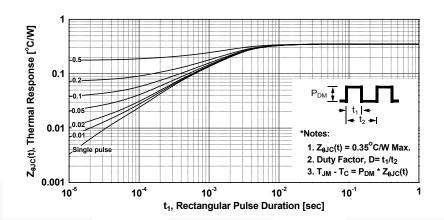


Figure 10. Maximum Drain Current vs. Case Temperature



Typical Performance Characteristics (Continued)

Figure 12. Transient Thermal Response Curve



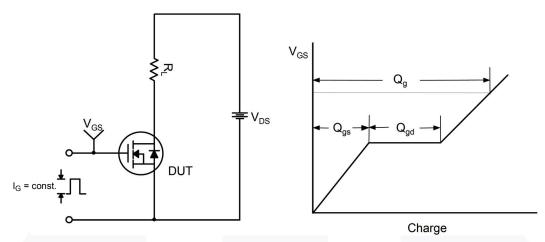


Figure 13. Gate Charge Test Circuit & Waveform

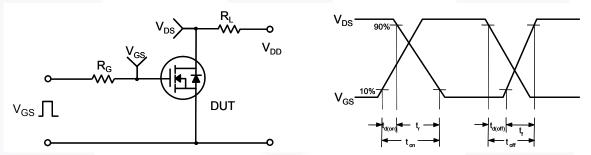


Figure 14. Resistive Switching Test Circuit & Waveforms

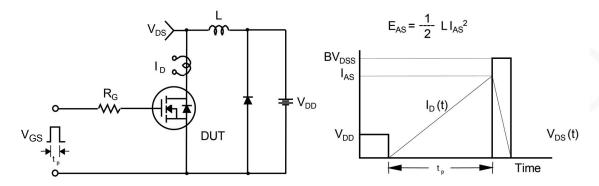


Figure 15. Unclamped Inductive Switching Test Circuit & Waveforms

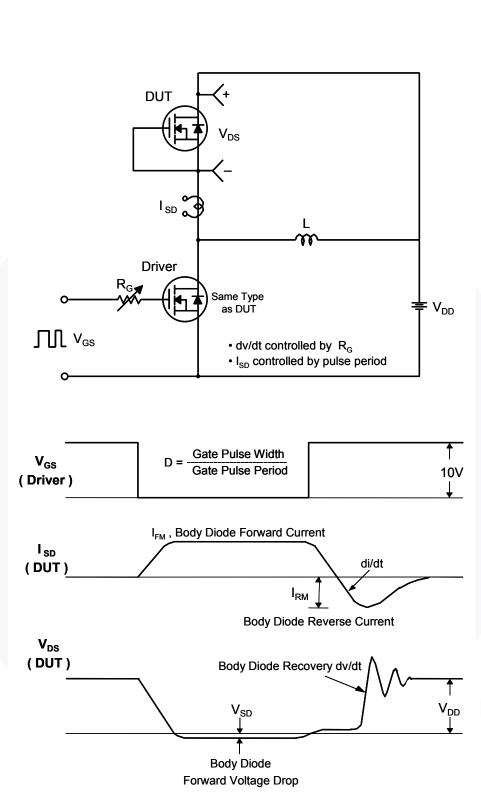
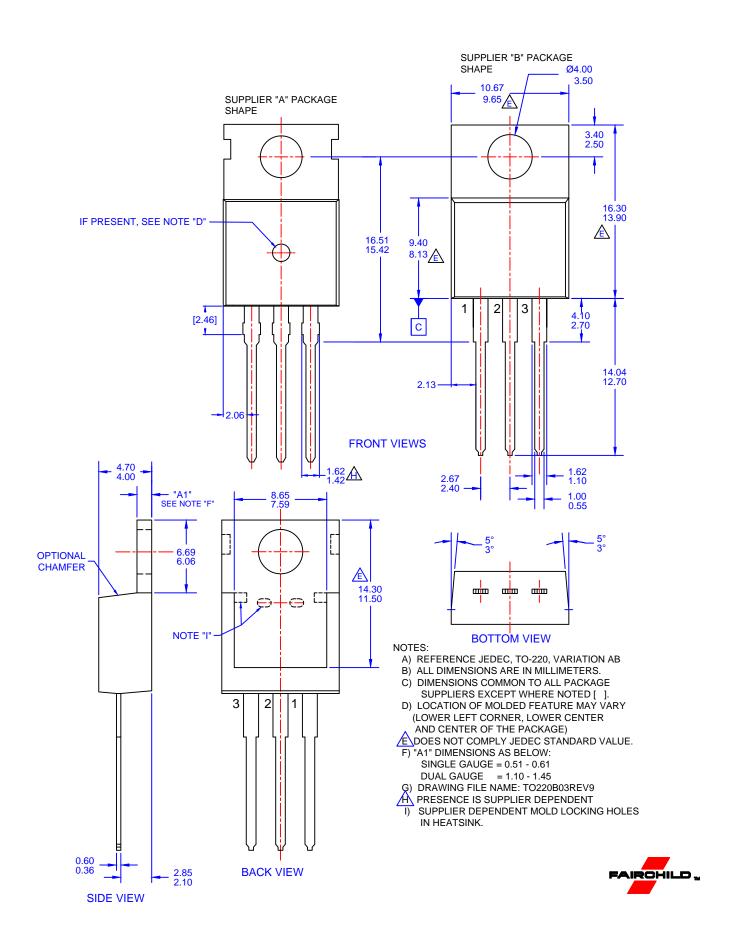


Figure 16. Peak Diode Recovery dv/dt Test Circuit & Waveforms



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